

10076244
02/13/2002

P

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

10076244
02/13/2002

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10076244	02/13/2002	438	108	2813	Nema Berezny

****APPLICANTS:** Aliyu Yakub; Chooi Simon; Zhou Meisheng; Sudijono John; Gupta Subhash; Roy Sudipto;

Nema has
the parent
case.

BEST AVAILABLE COPY

****CONTINUING DATA VERIFIED:**

This application is a CIP of 09/612,576 07/07/2000 ABN

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			CS99-343C
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Method of copper/copper surface bonding using a conducting polymer for application in IC chip bonding			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg.
Amount Due		Print Fig.	
Date Paid			
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
(Attached in pocket on right inside flap)